

## Excellent Integrated System Limited

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[Samsung Electro-Mechanics America, Inc.](#)  
[CL21CR82BBANNNC](#)

For any questions, you can email us directly:

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**SAMSUNG  
ELECTRO-MECHANICS**



## SPECIFICATION

- Supplier : Samsung electro-mechanics
- Product : Multi-layer Ceramic Capacitor

- Samsung P/N : **CL21CR82BBANNNC**
- Description : **CAP, 0.82pF, 50V, ±0.1pF, COG, 0805**

### A. Samsung Part Number

**CL 21 C R82 B B A N N N C**  
 ① ② ③ ④ ⑤ ⑥ ⑦ ⑧ ⑨ ⑩ ⑪

① Series	Samsung Multi-layer Ceramic Capacitor									
② Size	0805 (inch code)	L: 2.0 ± 0.1 mm	W: 1.25 ± 0.1 mm							
③ Dielectric	COG	⑧ Inner electrode		Ni						
④ Capacitance	0.82 pF	Termination		Cu						
⑤ Capacitance tolerance	±0.1 pF	Plating		Sn 100% (Pb Free)						
⑥ Rated Voltage	50 V	⑨ Product		Normal						
⑦ Thickness	0.65 ± 0.1 mm	⑩ Special		Reserved for future use						
		⑪ Packaging		Cardboard Type, 7" reel						

### B. Samsung Reliability Test and Judgement condition

	Performance	Test condition
Capacitance	Within specified tolerance	1MHz±10% 0.5~5Vrms
Q	416.4 min	
Insulation Resistance	10,000Mohm or 500Mohm·μF Whichever is Smaller	Rated Voltage 60~120 sec.
Appearance	No abnormal exterior appearance	Microscope (×10)
Withstanding Voltage	No dielectric breakdown or mechanical breakdown	300% of the rated voltage
Temperature Characterisitcs	COG (From -55℃ to 125℃, Capacitance change should be within ±30PPM/℃)	
Adhesive Strength of Termination	No peeling shall be occur on the terminal electrode	500g-F, for 10±1 sec.
Bending Strength	Capacitance change : within ±5% or ±0.5pF whichever is larger	Bending to the limit (1mm) with 1.0mm/sec.
Solderability	More than 75% of terminal surface is to be soldered newly	SnAg3.0Cu0.5 solder 245±5℃, 3±0.3sec. (preheating : 80~120℃ for 10~30sec.)
Resistance to Soldering heat	Capacitance change : within ±2.5% or ±0.25pF whichever is larger Tan δ, IR : initial spec.	Solder pot : 270±5℃, 10±1sec.

	Performance	Test condition
<b>Vibration Test</b>	Capacitance change : within $\pm 2.5\%$ or $\pm 0.25\text{pF}$ whichever is larger Tan $\delta$ , IR : initial spec.	Amplitude : 1.5mm From 10Hz to 55Hz (return : 1min.) 2hours $\times$ 3 direction (x, y, z)
<b>Moisture Resistance</b>	Capacitance change : within $\pm 7.5\%$ or $\pm 0.75\text{pF}$ whichever is larger Q : 102.73 min IR : 500Mohm or $25\text{Mohm} \cdot \mu\text{F}$ Whichever is Smaller	With rated voltage $40\pm 2^\circ\text{C}$ , 90~95%RH, 500+12/-0hrs
<b>High Temperature Resistance</b>	Capacitance change : within $\pm 3\%$ or $\pm 0.3\text{pF}$ whichever is larger Q : 208.2 min IR : 1000Mohm or $50\text{Mohm} \cdot \mu\text{F}$ Whichever is Smaller	With 200% of the rated voltage Max. operating temperature 1000+48/-0hrs
<b>Temperature Cycling</b>	Capacitance change : within $\pm 2.5\%$ or $\pm 0.25\text{pF}$ whichever is larger Tan $\delta$ , IR : initial spec.	1 cycle condition Min. operating temperature $\rightarrow 25^\circ\text{C}$ $\rightarrow$ Max. operating temperature $\rightarrow 25^\circ\text{C}$  5 cycle test

**C. Recommended Soldering method :**

Reflow ( Reflow Peak Temperature :  $260\pm 0/-5^\circ\text{C}$ , 10sec. Max )

\* For the more detail Specification, Please refer to the Samsung MLCC catalogue.